

Specification Sheet

Model No. : ZJY129

Description : 2.4inch TFT LCD Screen resolution
240*320 TFT LCD With Touch Panel Size:36.72*48.96mm
Driver Chip ILI9341 interface 8/16bits parallel 37Pin
Voltage V Font Color Option Full Color ZJY129

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1. General Description

ZJY129 is a 240RGB*320 dots matrix TFT LCD module. It has a TFT panel composed of 720 sources and 320 gates. The LCM can be easily accessed by micro-controller.

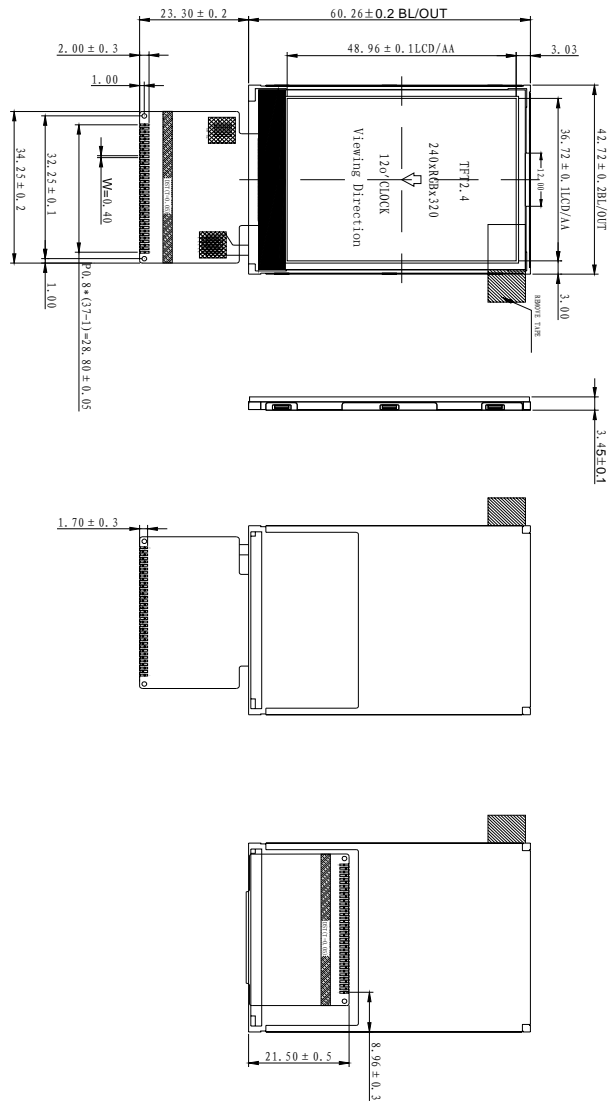
2. Features

Display Mode	Transmissive
	a-TFT
Display Format	Graphic 240RGB*320 Dot-matrix
Input Data	8 /16bits parallel interface
Viewing Direction	12 o'clock
Drive	ILI9341

3. Mechanical Specification

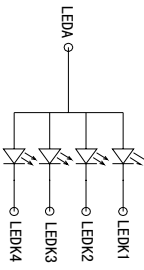
Item	Specifications	Unit
Dimensional outline	42.72(W)*60.26(H)*3.45+/-0.1(T) (FPC not include)	mm
Resolution	240RGB*320	dots
LCD Active area	36.72(W)*48.96(H)	mm
Pixel size	0.153(W)*0.153(H)	mm

4. Mechanical Dimension



Pin	Description
1	DB0
2	DB1
3	DB2
4	DB3
5	GND
6	LVCC
7	VSS
8	RS
9	R/W
10	ABD
11	NC
12	KL
13	VI
14	XR
15	YD
16	LEDA
17	LEDK1
18	LEDK2
19	LEDK3
20	LEDK4
21	PA/RK
22	DB4
23	DB10
24	DB11
25	DB12
26	DB13
27	DB14
28	DB15
29	DB16
30	DB17
31	RESSET
32	VCC
33	LVCC
34	GND
35	DB5
36	DB6
37	DB7

- NOTES:
1. DISPLAY TYPE: TFT
 2. OPERATING TEMP: $-10^{\circ}\text{C} \sim 60^{\circ}\text{C}$
 3. STORAGE TEMP: $-20^{\circ}\text{C} \sim 70^{\circ}\text{C}$
 4. LCD DRIVER: COG(IC: **ILI9341**);
 5. BACKLIGHT: 4 CHIP-WHITE LED (Parallel)
 6. GENERAL TOLERANCE: ± 0.20
 7. ROHS



CIRCUIT DIAGRAM
(I=60MA V=3.0-3.4V)

ICbanQ Inc.		d	
LCM			
v0.2	MM		
2/013, 05, 06	1:1		
UNMARKED TOLERANCE: ± 0.20 mm			1 OF 1

5. Maximum Ratings

Item	Symbol	Min	Max	Unit	Note
Supply voltage	V	-0.3	4.6	V	
Operating temperature	V _T	-0.3	V _{CC} +0.3	V	
Storage temperature	T _{OPR}	-20	70	°C	
Storage temperature	T _{STR}	-30	80	°C	

6. Electrical Characteristics

Item		Symbol	Condition	Min.	Typ.	Max.	Unit
Supply voltage	Logic	V _{CC}		2.7	2.8	3.3	V
Input Voltage	H level	T _{IH}		0.8*IOVCC		IOVCC	V
	L level	T _{IL}		-0.3		0.2* IOVCC	
Storage temperature		I _{DD}	With internal voltage generation V _{CC} =2.8V; T _{emp} =25°C			TBD	mA

7. Backlight Characteristic

Item	Symbol	Min	Typical	Max	Unit
LED module Forward voltage	V _{LED}	3.0	3.2	3.4	V
LED module current	V _{LED}		60		mA
L/G Surface Luminance ★1	L _S	3000			Cd/m ³
LCM Surface brightness uniform ★2	L _D	80			%

★ 1 Test condition is:

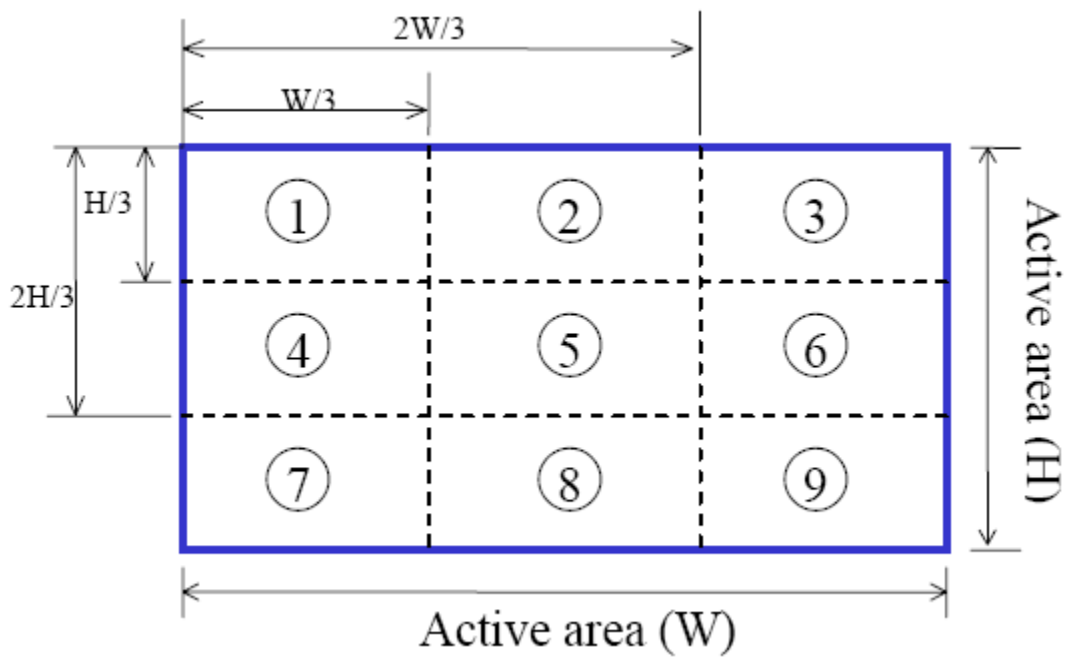
- (a) Center point on active area.
- (b) Best Contrast.

★2 Uniform measure condition:

(1) Measure 9 point. Measure location show below;

(2) Uniform = (Min. brightness / Max. brightness) * 100%

(3) Best Contrast.



8. Module Function Description

8.1 Pin Descriptions

PIN No.	Symbol	Description
1-4	DB0-DB3	Data bus <i>Fix to GND level when not in use</i>
5	GND	Ground
6	IOVCC	Power supply for LCM (2.8V-3.3V)
7	/CS	Chip select pin ("Low" enable)
8	RS	This pin is used to select "Data or Command" in the parallel interface When RS= '1', data is selected. When RS= '0', command is selected.
9	/WR	Serves as a write signal and <i>Fix to IOVCC level when not in use.</i>
10	/RD	Serves as a read signal and MCU read data at the rising edge. <i>Fix to IOVCC level when not in use.</i>
11	NC	No connection
12	XL	Touch panel control pin
13	YU	Touch panel control pin
14	XR	Touch panel control pin
15	YD	Touch panel control pin

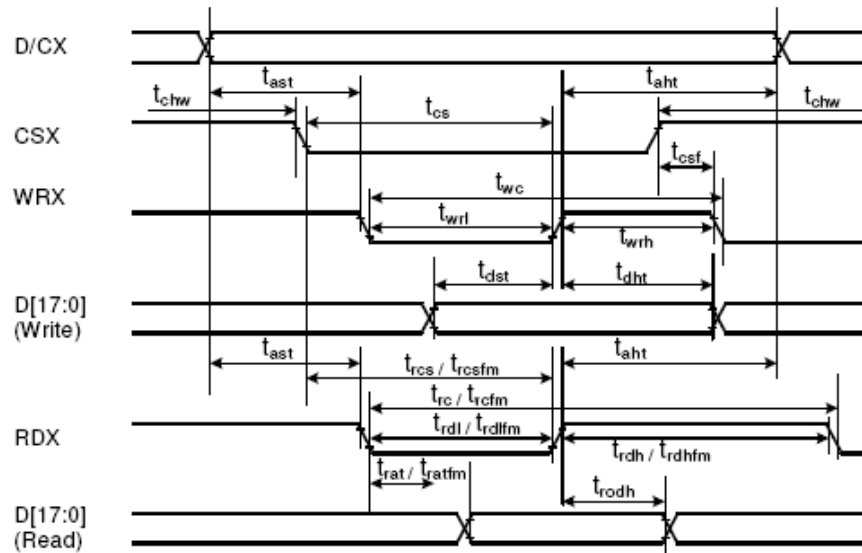
16	LEDA	Anode of Backlight (3.0V-3.4V Typical:3.2V)
17	LEDK1	Cathode of Backlight
18	LEDK2	Cathode of Backlight
19	LEDK3	Cathode of Backlight
20	LEDK4	Cathode of Backlight
21	FMARK	Tearing effect output pin to synchronize MPU to frame writing, activated by SW command. When this pin is not activated, this pin is low. If not used, open this pin.
22	DB4	Data bus <i>Fix to GND level when not in use</i>
23-30	DB8-DB15	Data bus <i>Fix to GND level when not in use</i>
31	/RESET	LCM Reset pin Signal is active low.
32	VCC	Power supply for LCM (2.8V-3.3V)
33	IOVCC	Power supply for LCM (2.8V-3.3V)
34	GMD	Ground
35-37	DB5-DB7	Data bus <i>Fix to GND level when not in use</i>

About the power supply instructions:

IOVCC and VCC are connected together with 2.8V-3.3V; the backlight LED can be powered separately (3.0-3.4 V), or it can share a set of voltages with VCC (A is connected to VCC and K is connected as negative ground).

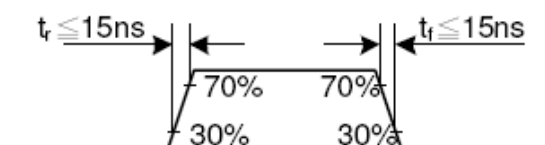
8.2 Timing characteristics.

Display Parallel 18/16/9/8-bit Interface Timing Characteristics(8080- II system)

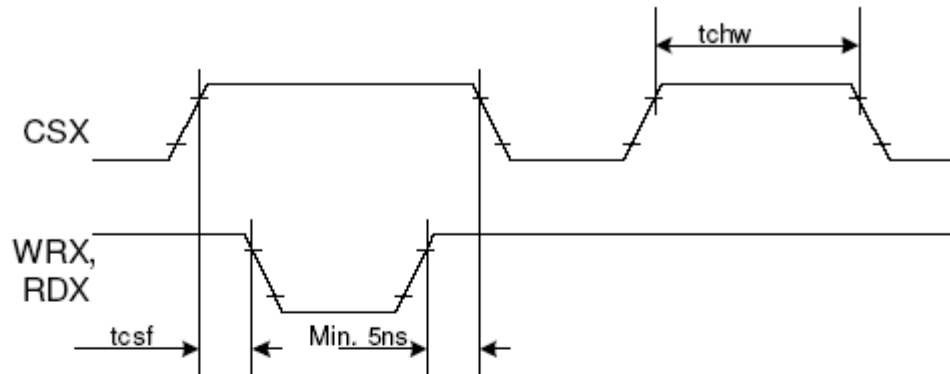


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[17:10]&D[8:1], D[17:10], D[17:9]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

Note: $T_a = -30$ to 70 °C, $V_{DDI} = 1.65V$ to $3.3V$, $V_{CI} = 2.5V$ to $3.3V$, $V_{SS} = 0V$.

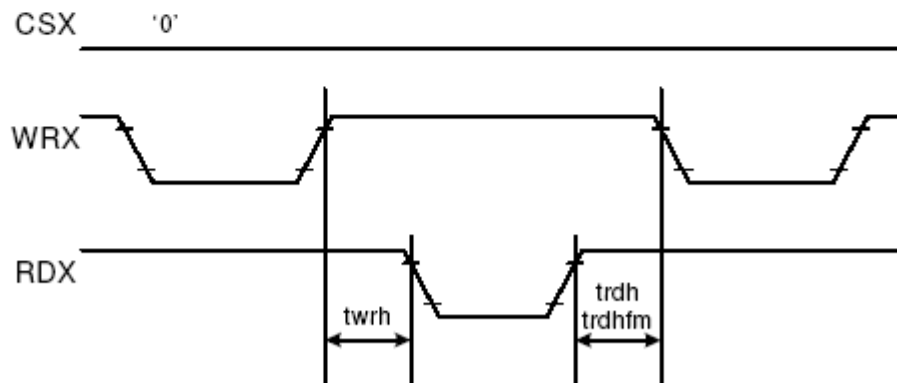


CSX timings :



Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Write to read or read to write timings:



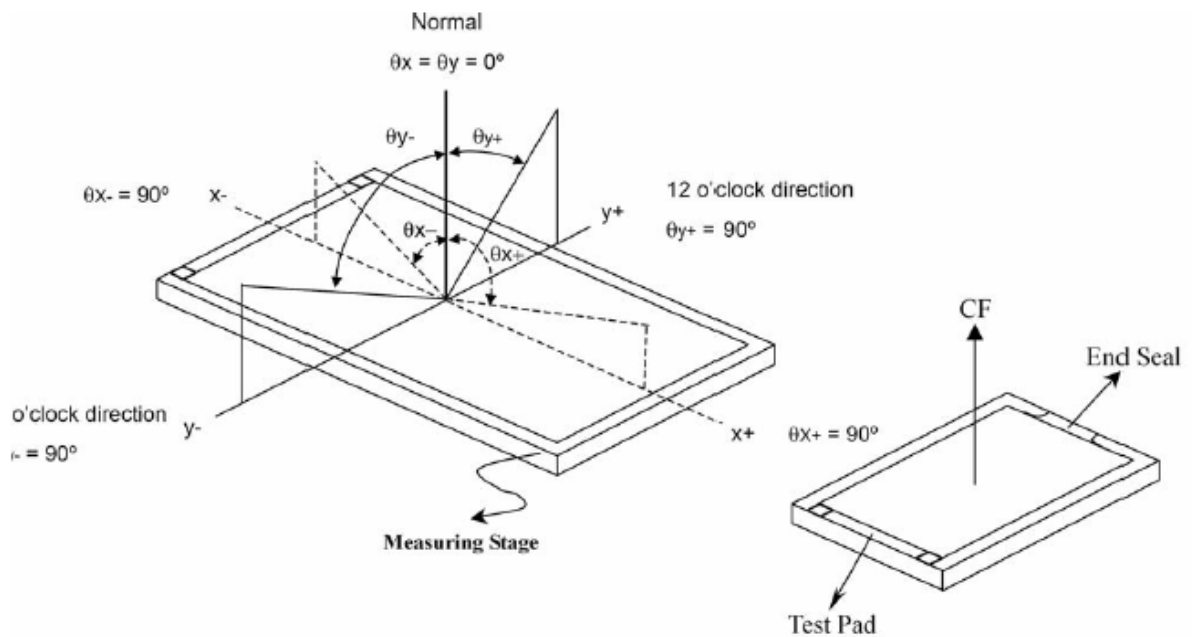
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

9. Electro-optical Characteristics

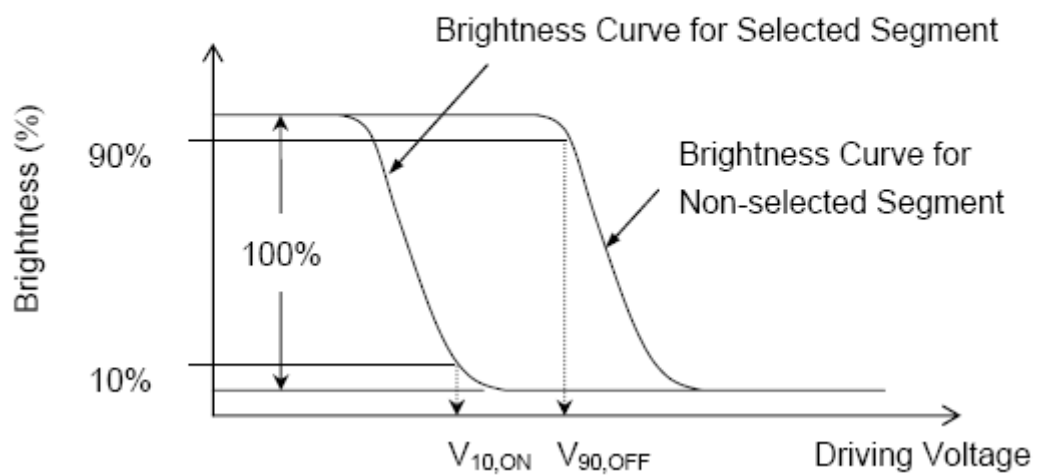
Item	Symbol	Conditions	Temp	Min.	Typ.	Max.	Unit	Note
Response Time	T_R	$\theta = \phi = 0$	25°C		TBD	TBD	msec	NOTE2
	T_F				TBD	TBD		
Viewing Angle Range	$\phi = 0^\circ (6'')$	$\phi = 90^\circ (3'')$		$\phi = 180^\circ (12'')$		$\phi = 270^\circ (9'')$		NOTE3
$\theta (25^\circ\text{C}) \text{ CR} \geq 10$	TBD	TBD		TBD		TBD		NOTE3

The above "viewing angle" is the measuring position with the largest contrast ratio. Not for good image quality. Viewing direction for good image quality is 12 O'clock.

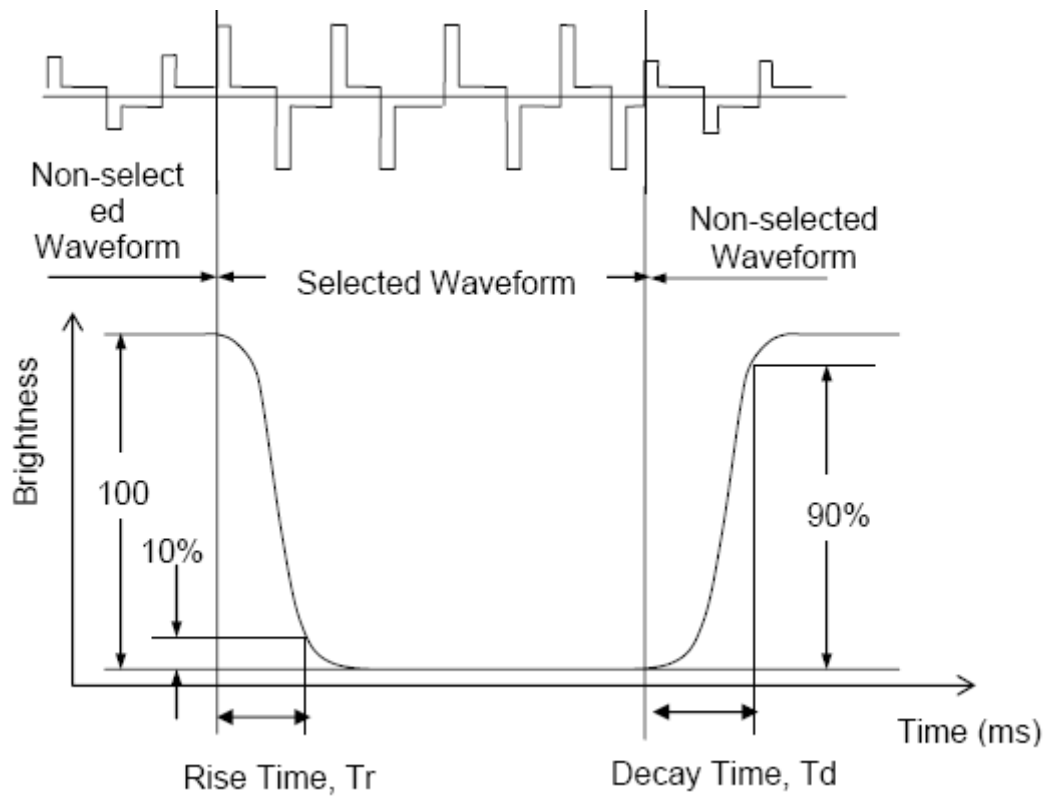
- For panel only
- Electro-Optical Characteristics Test Method



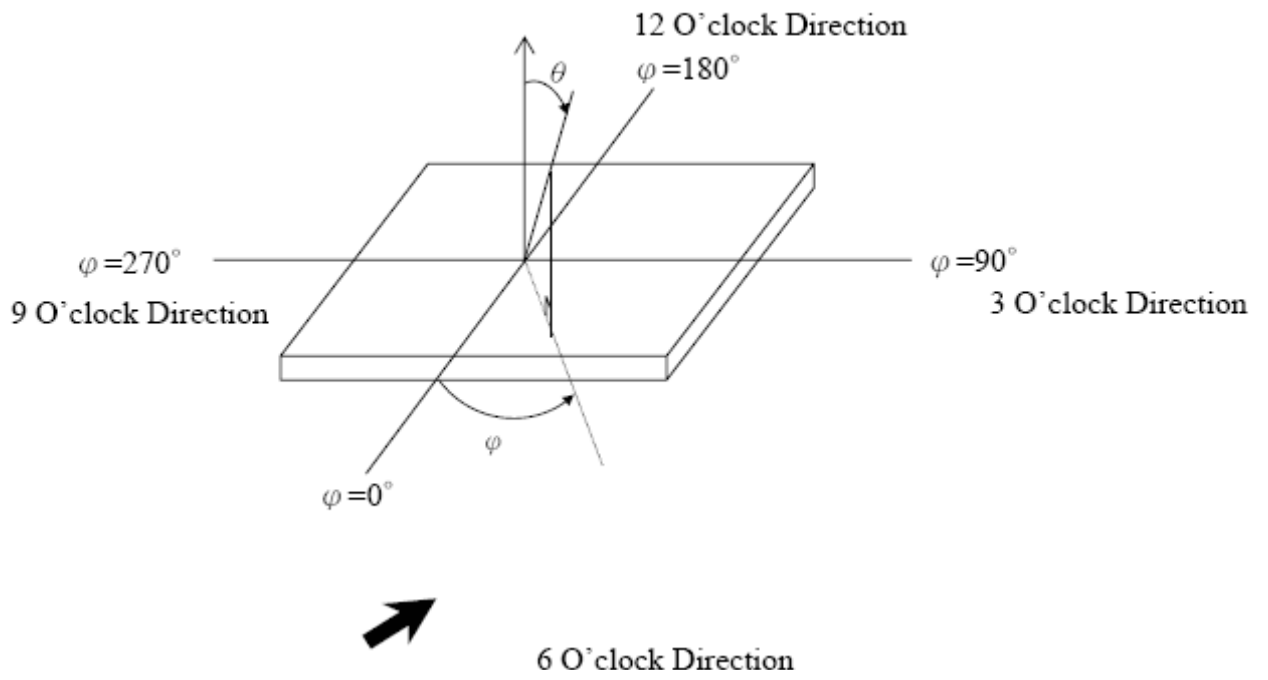
$$V_{op} = (V_{10,ON} + V_{90,OFF})/2$$



.Note2.Definition of Optical Response Time:

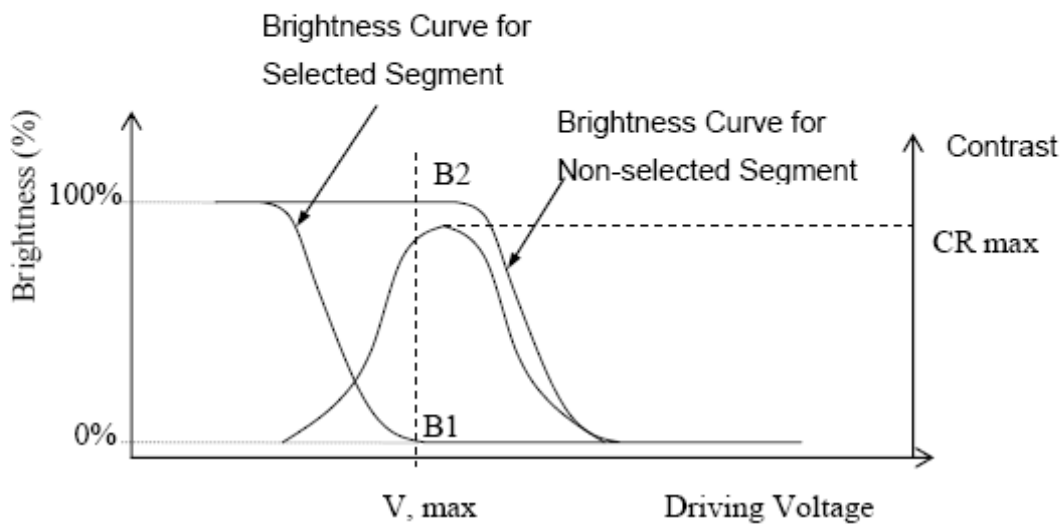


.Note3.Definition of Viewing Angle θ and ϕ :



Note4. Definition of Contrast ratio (CR):

$$CR = \frac{\text{Brightness of Non-selected Segment (B2)}}{\text{Brightness of Selected Segment (B1)}}$$



10. Reliability

10.1Mtbf

The LCD module shall be designed to meet a minimum MTBF value of 50000 hours with normal

10.2Test condition

NO.	ITEM	CONDITION	CRITERION
1	High Temperature Non-Operating Test	80°C*240Hrs	<ul style="list-style-type: none"> ◦ No Defect Of Operational Function In Room Temperature Are Allowable ◦ IDD of LCM in Pre-and Post-Test Should Follow Specification
2	Low Temperature Non-Operating Test	-30°C*240Hrs	
3	High Temperature/Humidity Non Operating Test	60°C*90%RH*240Hrs	
4	High Temperature Operating Test	70°C*240Hrs	
5	Low Temperature Operating Test	-20°C*240Hrs	
6	Thermal Shock Test	-20°C (30Min) ↔70°C (30Min) *10CYCLES	

Notes:

1. Judgments should be made after exposure in room temperature for two hours.
2. The distill water is used for the high temperature/humidity test.
3. The sample above is individually for every reliability tests condition.

11. Inspection standards

1. AQL (Acceptable Quality Level)

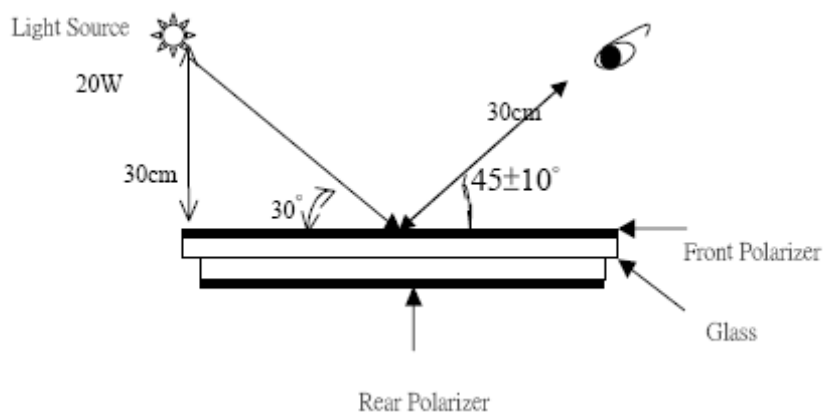
AQL of major and minor defect.

	MAJOR DEFECT	MINOR DEFECT
AQL	0.65	1.5

2. Basic conditions for inspection

The LCM face to us, in normal environment, the lux is 1000 ± 200 . (Darkroom's lux: 100 ± 50), About an angle of incidence 30° , a distance of 30 cm with an angle of $45 \pm 10^\circ$ to check the products without uncovering the film!

(As shown below)

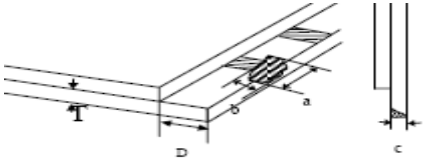
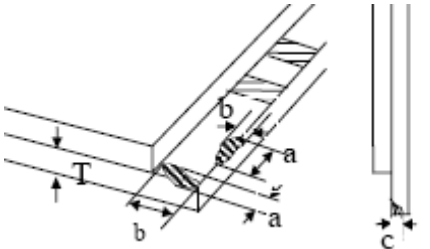
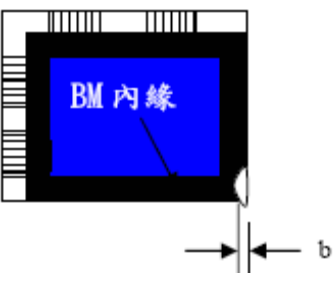


3. Inspection item and criteria

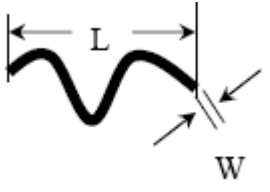
3.1 Visual inspection criterion in immobility

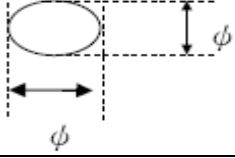
3.1.1 Glass defect

NO	Defect item	Criteria	Remark
1	Dimension Unconformity (Major defect)	By Engineering Drawing	
2	Cracks (Major defect)	1. Linear cracks panel 2. Nonlinear crack contrast by limited sample	<div style="display: flex; align-items: center;"> <div style="margin-right: 10px;">【Reject】</div> </div>
3	Glass extrude the conductive area (minor defect)	a: disregards and no influence assemblage. 1) $b \leq 1/3$ Pin width (non bonding)	A: Length, b: Width


		area) 2)bonding area $\leq 0.5\text{mm}$	【Accept】 【Accept】	
4	Pin-side ,conductive area damaged (minor defect)	(a c: disregards) $b \leq 1/3$ of effective length for bonding electrode	【Accept】	a: length, b: Width, c: Thickness 
5	Pin-side,non-conductive area damaged (minor defect)	1)Damage area don't touch the ITO (Inclueling contraposition mark, except scribing mark) 2) $C < T$ $b \cong BM1/3$ of width 3) $c = T$ b not touch the seal glue 4)a disregards	【Accept】 【Accept】 【Accept】	a: Length, b: Width c: Thickness 
6	Non-pin-side damage (minor defect)	$c < T$ 1)b exceeds $1/3B_m$ $c = T$ b not touch the seal glue	【Reject】 【Reject】	c: Thickness b: width of  damage

3.1.2LCD appearance defect(View area)

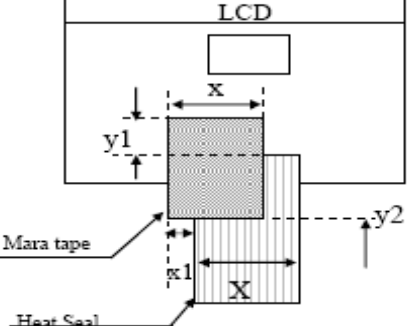
NO	Defect item	Criteria		Remark
		Specification	Allowable	
1	Fiber、 glass cratch、 polarizer scratch/folded (minor defect)	$W \leq 0.03\text{mm}$	disregard	note1:L: Length, W: Width note2: disregard if out of AA 
		$0.03\text{mm} < W \leq 0.05\text{mm};$ $L \leq 3.0\text{mm}$	2	
		$0.05\text{mm} < W \leq 0.1\text{mm};$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm}; L > 3.0\text{mm}$	0	

2	Polarizer bubble、 concave and convex (minor defect)	$\phi \leq 0.2\text{mm}$	disregard	note1: $\phi = (L+W)/2$, L:Length, W :Width note2:disregard if out of AA
		$0.2\text{mm} < \phi \leq 0.3\text{mm}$	2	
		$0.3\text{mm} < \phi \leq 0.5\text{mm}$	1	
		$0.5\text{mm} < \phi$	0	
3	Black dots、dirty dots、 impurities、eye winker (minor defect)	$\phi \leq 0.15\text{mm}$	disregard	note2:disregard if out of AA 
		$0.15\text{mm} < \phi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \phi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \phi$	0	
4	Polarizer prick (minor defect)	$\phi \leq 0.1\text{mm}$	disregard	note1: $\phi = (L+W)/2$, L=Length, W=Width note2:the distance between two dots>5mm
		$0.1\text{mm} < \phi \leq 0.25\text{mm}$	3	
		$\phi > 0.25\text{mm}$	0	

3.1.3FPC

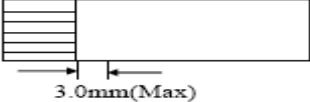
NO	Defect item	Criteria		Remark
1	Copper screen peel (minor defect)	Copper screen peel	【Reject】	
2	No release tape or peel	No release tape or peel	【Reject】	
3	Dirty dot and impurity of FPC for customer using side (minor defect)	Specification	Allowable	Note1: Cannot have stride ITO impurities
		$\phi \leq 0.25\text{mm}$	2	
		$\phi > 0.25$	0	

3.1.4Black tape & Mara tape

NO	Defect item	Criteria	Remark
1	FPC or H/S black tape (minor defect)	1. shift spec: 1) glue to the polarize 【Reject】 2) IC bare 【Reject】 2. left-and-right spec: 1) exceed of FPC edge or H-S edge 【Reject】 2) IC bare 【Reject】	

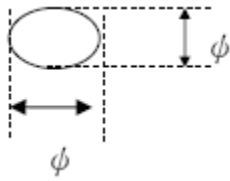
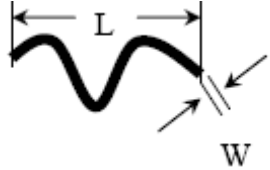
2	No black tape (major defect)	No black tape 【Reject】	
3	Tape position mistake (minor defect)	Not by engineering drawing	
4	Mara tape defect (minor defect)	Peel before pulling the protecting film 【Reject】	

3.1.5 Silicon and Taffy glue

NO	Defect item	Criteria	Remark
1	Quantity of silicon (major defect)	Uncover the ITO and circuit area 【Reject】	note: compared by engineering
2	Taffy glue (major defect)	1.Uncover the reveal copper area【Reject】 2.Cover layer 0.3mm(Min)~3.0mm(Max) 【Reject】	note: if customer has special requirement, refer to the technical document 
3	Depth of glue covering (major defect)	Depth of glue covering ovetop front Polarizer 【Reject】	Except of the special requirement

3.2Electrical criteria

NO	Defect item	Criteria	Remark
1	No display (major defect)	No display 【Reject】	
2	Missing line (major defect)	Missing line 【Reject】	
3	Seg-com light and dark (major defect)	Seg-com light and dark 【Reject】	ND filter 2% test
4	No display in immobility (major defect)	No display in immobility 【Reject】	
5	Flicker of Pattern (major defect)	Flicker of Pattern 【Reject】	
6	Mura (major defect)	ND filter 2%test	
7	Over current	Over current	

	(major defect)	【Reject】		
8	Voltage out of specification (major defect)	Voltage out of specification 【Reject】		
9	Pattern blur, error code (major defect)	Pattern blur, error code 【Reject】		
10	Dark light, Flicker (major defect)	Dark light, Flicker 【Reject】		
11	Black/white dots、 Dirty dots、 eye winker (major defect)	Specification	Allowable	Note1:disregard if out of AA 
		$\phi \leq 0.15\text{mm}$	disregard	
		$0.15\text{mm} < \phi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \phi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \phi$	0	
12	Fiber、glass crutch、Polarizer scratch/folded (major defect)	$W \leq 0.03\text{mm}$	disregard	Note1:L: Length, W: Width Note2: disregard if out of AA 
		$0.03\text{mm} < W \leq 0.05\text{mm}$ $L \leq 3.0\text{mm}$	2	
		$0.05\text{mm} < W \leq 0.1\text{mm}$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm}; L > 3.0\text{mm}$	0	

12.Precautions for using LCD modules.

12.1 Safety

- (1)Do not swallow any liquid crystal ,even if there is no proof that liquid crystal is poisonous.
- (2)If the LCD panel breaks, be careful not to get liquid crystal to touch your skin.
- (3)If skin is exposed to liquid crystal, wash the area thoroughly with alcohol or soap.

12.2Srorang Conditions

- (4)Store the panel or module in a dark place where the temperature is $23 \pm 5^\circ\text{C}$ and the humidity is below $45 \pm 20\% \text{RH}$.
- (5)Store in anti-static electricity container.

-
- (6) Store in clean environment, free from dust, active gas, and solvent.
(7) Do not place the module near organics solvents or corrosive gases.
(8) Do not crush, shake, or jolt the module.

12.3 Handling Precautions

- (9) Avoid static electricity, which can damage the CMOS LSI.
(10) The polarizing plate of the display is very fragile, please handle it very carefully.
(11) Do not give external shock.
(12) Do not apply excessive force on the surface.
(13) Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of the plate.
(14) Do not use ketonic solvent & Aromatic solvent, use with a soft cloth soaked with a cleaning naphtha solvent.
(15) Do not operate it above the absolute maximum rating.
(16) Do not remove the panel or frame from the module.

12.4 Warranty

The period is within twelve months since the date of shipping out under normal using and storage conditions.

13. Factory

FACTORY NAME:

FACTORY ADDRESS:

FACTORY PHONE:

14. Revision history

Version	Revise record	Date
v0.0	Original version	2014-02-18
v0.1	Changed backlight	2014-04-28
v0.2	Changed touch panel	2014-05-06